

CLAIMS

1. A resin encapsulating method for a semiconductor chip comprising adhering a pressure-sensitive adhesive tape to a leadframe, bonding a semiconductor chip to the leadframe having the pressure-sensitive adhesive tape adhered thereto, encapsulating the semiconductor chip with a resin in a mold, and stripping the pressure-sensitive adhesive tape, wherein the pressure-sensitive adhesive tape has a thermal shrinkage of 3% or less on resin encapsulating.

2. A resin encapsulating method for a semiconductor chip according to claim 1, wherein a tape carrier film is used in place of the leadframe.

3. A pressure-sensitive adhesive tape to be adhered to a leadframe and the like, which is used in the resin encapsulating method for a semiconductor chip according to claim 1 or 2 and has a thermal shrinkage of 3% or less on resin encapsulating.